Nidec Advance Technology Corporation

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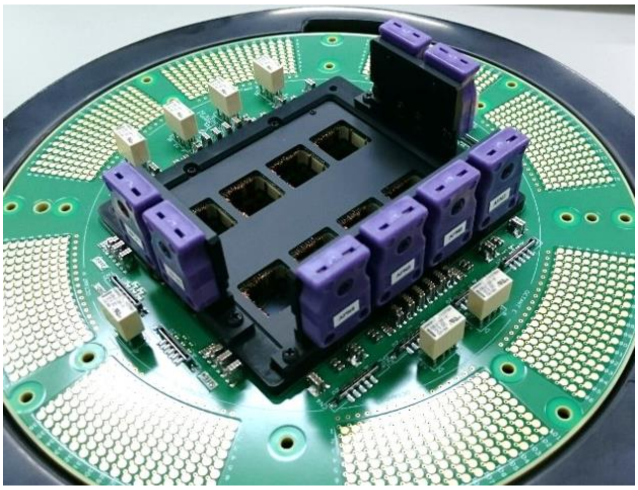
# Nidec Advance Technology Launched a Semiconductor Device Temperature Measurement Probe, a Chamber Head Type Probe Card for High Voltage application

Nidec Advance Technology Corporation ("Nidec Advance Technology" or the "Company"), a Nidec Group company, announced today that it has launched, (1) a Semiconductor Device Temperature Measurement Probe, (2) a Chamber Head Type Probe Card for High Voltage application.

Recent years, demand for power semiconductors used in electric vehicles (EVs) and industrial equipment has increased, leading to a growing need for more accurate, high-quality inspection of power semiconductors that handle high voltages and currents, especially under high temperatures.

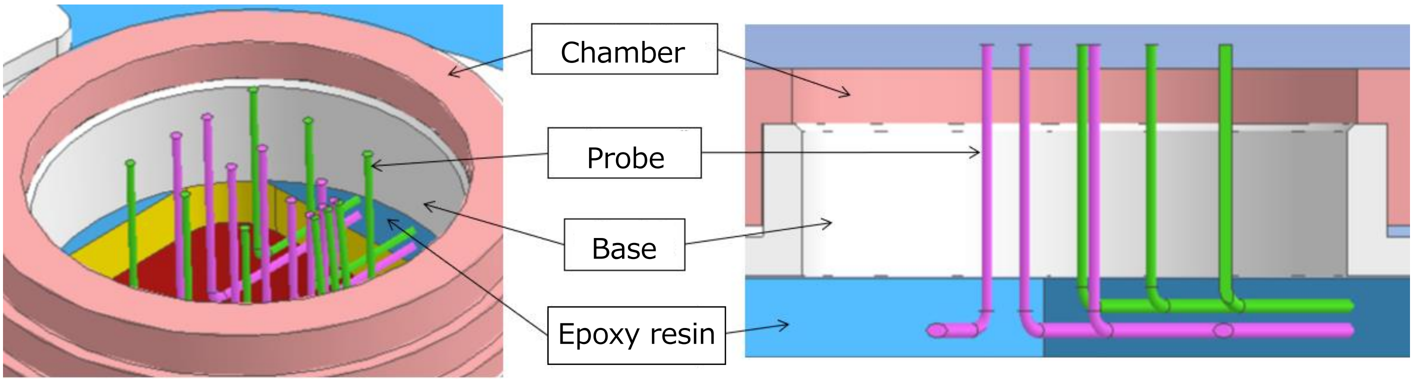
## (1) TC (Thermo Couple) probe

Semiconductor Device Temperature Measurement Probe introduce a thermocouples technology "TC (Thermo Couple) probe" into probe card. This TC probes contact existing PAD and provide a quite accurate device surface temperature measurement solution during wafer testing.



## (2) Chamber Head type Probe Card

Chamber Head type Probe Card is a probe card with a pressurized chamber structure that can increase the withstand voltage while the pitch between contact terminals is narrowing with the demand for miniaturization of devices. By filling various gases using our unique technology, this probe card prevents a damage to devices caused by discharge. By filling with nitrogen gas, it is possible to prevent the damage caused by discharge and also to suppresses oxidation of the probe and device during testing. This help to extend a life of the probe and improving a contact performance to test the device.



We will continue to develop the new product with new and assets of technologies, provide more valuable contact solutions for semiconductor device wafer testing.

**For more details on the above product, please contact:** PC Division, Nidec Advance Technology Corporation. +81-75-280-8100. Thank you